

DATA SHEET

BFT92W

PNP 4 GHz wideband transistor

Product specification

May 1994



PNP 4 GHz wideband transistor

BFT92W

FEATURES

- High power gain
- Gold metallization ensures excellent reliability
- SOT323 (S-mini) package.

APPLICATION

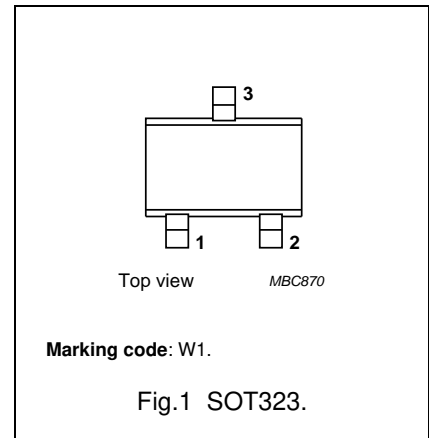
It is intended as a general purpose transistor for wideband applications up to 2 GHz.

DESCRIPTION

Silicon PNP transistor in a plastic, SOT323 (S-mini) package. The BFT92W uses the same crystal as the SOT23 version, BFT92.

PINNING

PIN	DESCRIPTION
1	base
2	emitter
3	collector



QUICK REFERENCE DATA

SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
V_{CBO}	collector-base voltage	open emitter	–	–	–20	V
V_{CEO}	collector-emitter voltage	open base	–	–	–15	V
I_C	collector current (DC)		–	–	–35	mA
P_{tot}	total power dissipation	up to $T_s = 93\text{ }^\circ\text{C}$; note 1	–	–	300	mW
h_{FE}	DC current gain	$I_C = -15\text{ mA}$; $V_{CE} = -10\text{ V}$	20	50	–	
C_{re}	feedback capacitance	$I_C = 0$; $V_{CB} = -10\text{ V}$; $f = 1\text{ MHz}$	–	0.5	–	pF
f_T	transition frequency	$I_C = -15\text{ mA}$; $V_{CE} = -10\text{ V}$; $f = 500\text{ MHz}$	–	4	–	GHz
G_{UM}	maximum unilateral power gain	$I_C = -15\text{ mA}$; $V_{CE} = -10\text{ V}$; $f = 500\text{ MHz}$; $T_{amb} = 25\text{ }^\circ\text{C}$	–	17	–	dB
F	noise figure	$I_C = -5\text{ mA}$; $V_{CE} = -10\text{ V}$; $f = 500\text{ MHz}$	–	2.5	–	dB
T_j	junction temperature		–	–	150	$^\circ\text{C}$

Note

1. T_s is the temperature at the soldering point of the collector pin.

PNP 4 GHz wideband transistor

BFT92W

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V _{CB0}	collector-base voltage	open emitter	–	–20	V
V _{CEO}	collector-emitter voltage	open base	–	–15	V
V _{EBO}	emitter-base voltage	open collector	–	–2	V
I _C	collector current (DC)		–	–25	mA
P _{tot}	total power dissipation	up to T _s = 93 °C; note 1	–	300	mW
T _{stg}	storage temperature		–65	+150	°C
T _j	junction temperature		–	150	°C

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th j-s}	thermal resistance from junction to soldering point	up to T _s = 93 °C; note 1	190	K/W

Note to the “Limiting values” and “Thermal characteristics”

1. T_s is the temperature at the soldering point of the collector pin.

CHARACTERISTICST_j = 25 °C (unless otherwise specified).

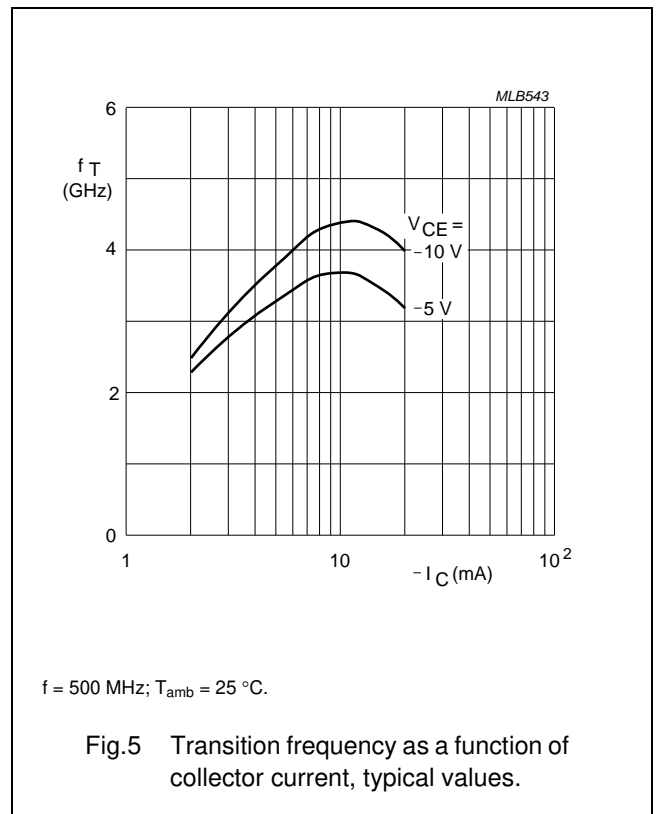
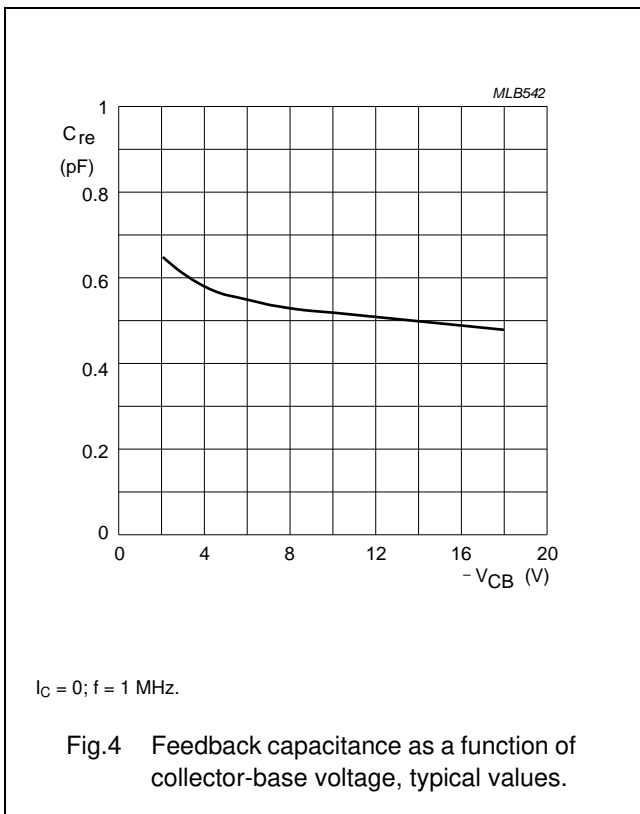
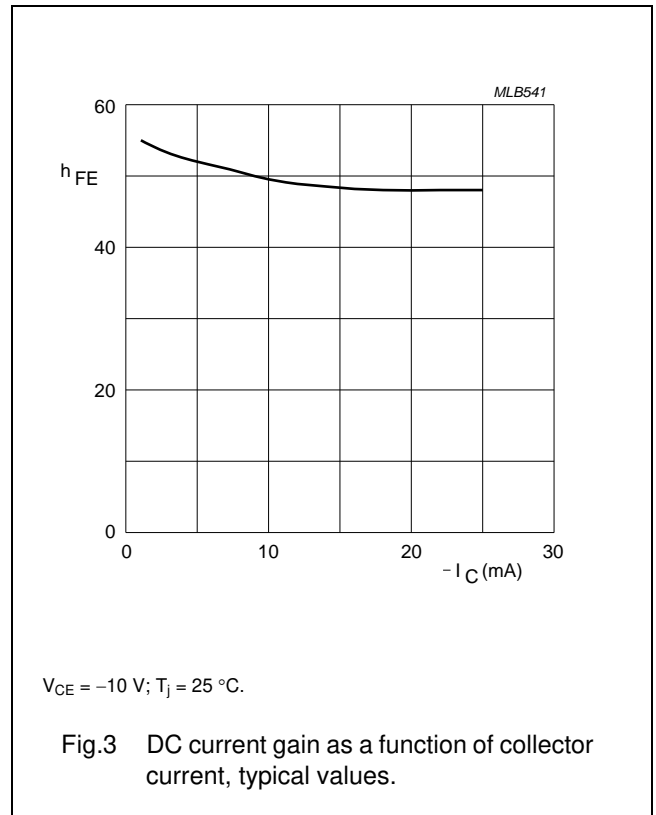
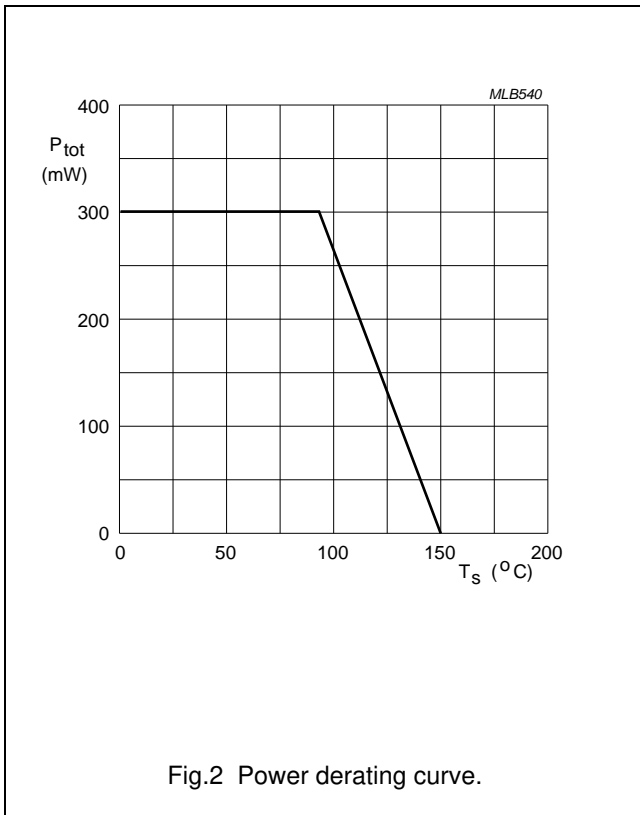
SYMBOL	PARAMETER	CONDITIONS	MIN.	TYP.	MAX.	UNIT
I _{CBO}	collector cut-off current	I _E = 0; V _{CB} = –10 V	–	–	–50	nA
h _{FE}	DC current gain	I _C = –15 mA; V _{CE} = –10 V	20	50	–	
f _T	transition frequency	I _C = –15 mA; V _{CE} = –10 V; f = 500 MHz; T _{amb} = 25 °C	–	4	–	GHz
C _c	collector capacitance	I _E = i _e = 0; V _{CB} = –10 V; f = 1 MHz	–	0.65	–	pF
C _e	emitter capacitance	I _C = i _c = 0; V _{EB} = –0.5 V; f = 1 MHz	–	0.75	–	pF
C _{re}	feedback capacitance	I _C = 0; V _{CB} = –10 V; f = 1 MHz	–	0.5	–	pF
G _{UM}	maximum unilateral power gain; note 1	I _C = –15 mA; V _{CE} = –10 V; f = 500 MHz; T _{amb} = 25 °C	–	17	–	dB
		I _C = –15 mA; V _{CE} = –10 V; f = 1 GHz; T _{amb} = 25 °C	–	11	–	dB
F	noise figure	Γ _s = Γ _{opt} ; I _C = –5 mA; V _{CE} = –10 V; f = 500 MHz	–	2.5	–	dB
		Γ _s = Γ _{opt} ; I _C = –5 mA; V _{CE} = –10 V; f = 1 GHz	–	3	–	dB

Note

1. G_{UM} is the maximum unilateral power gain, assuming s₁₂ is zero. $G_{UM} = 10 \log \frac{|s_{21}|^2}{(1 - |s_{11}|^2)(1 - |s_{22}|^2)}$ dB.

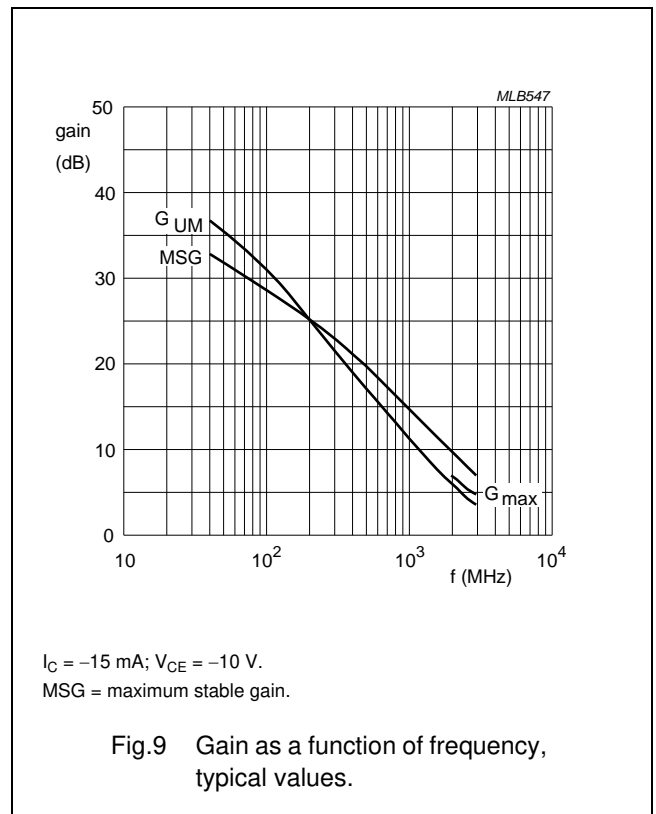
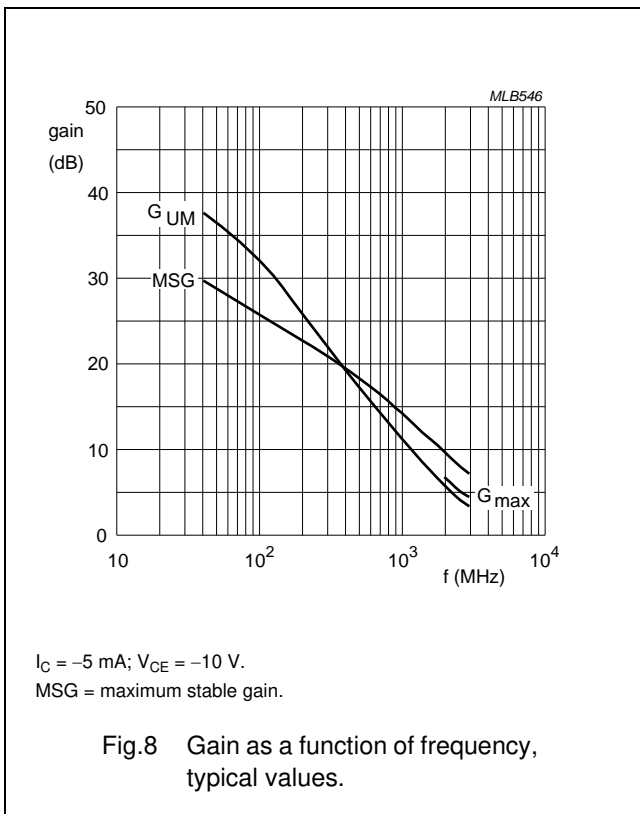
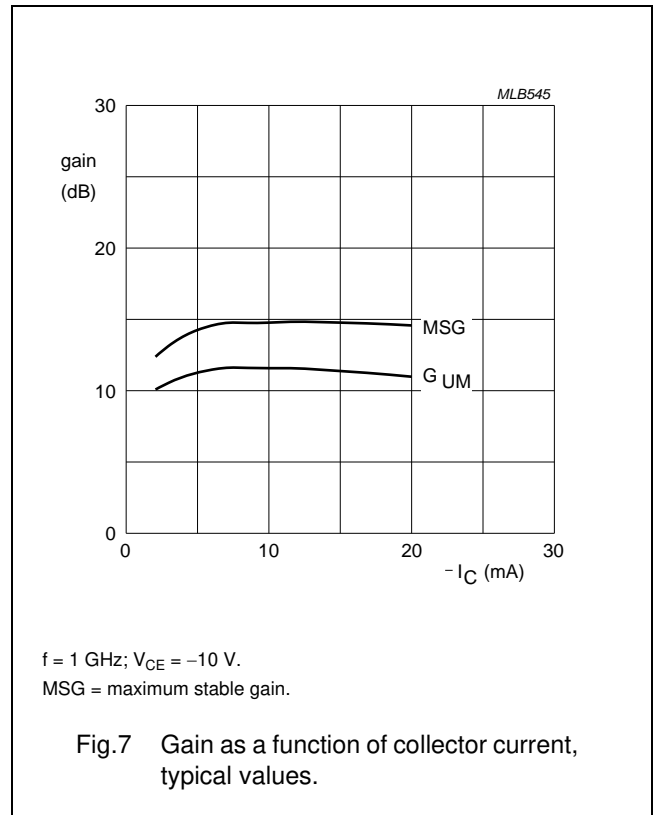
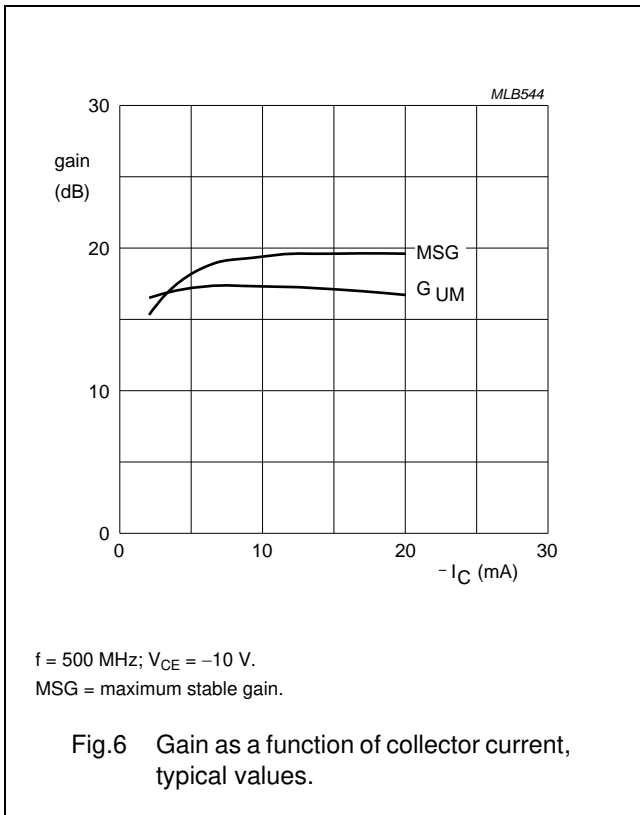
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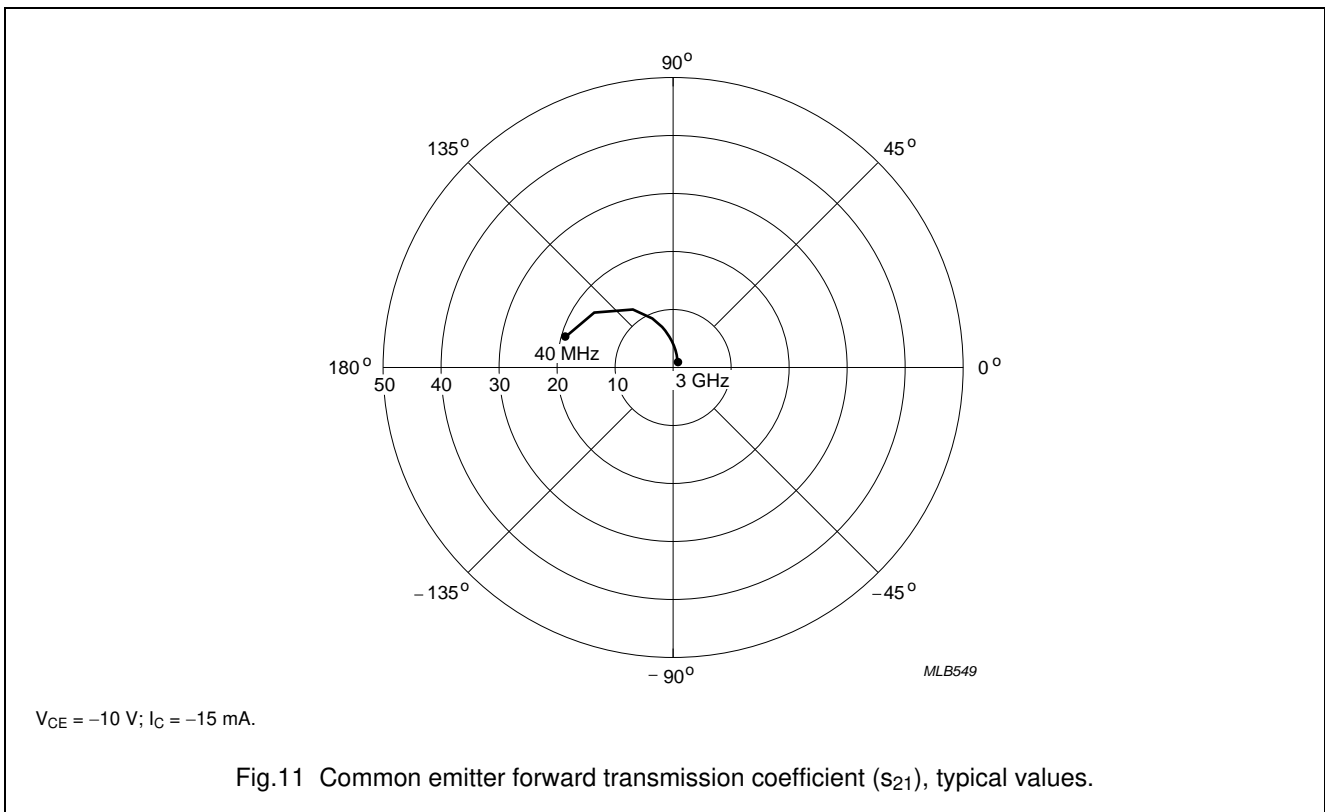
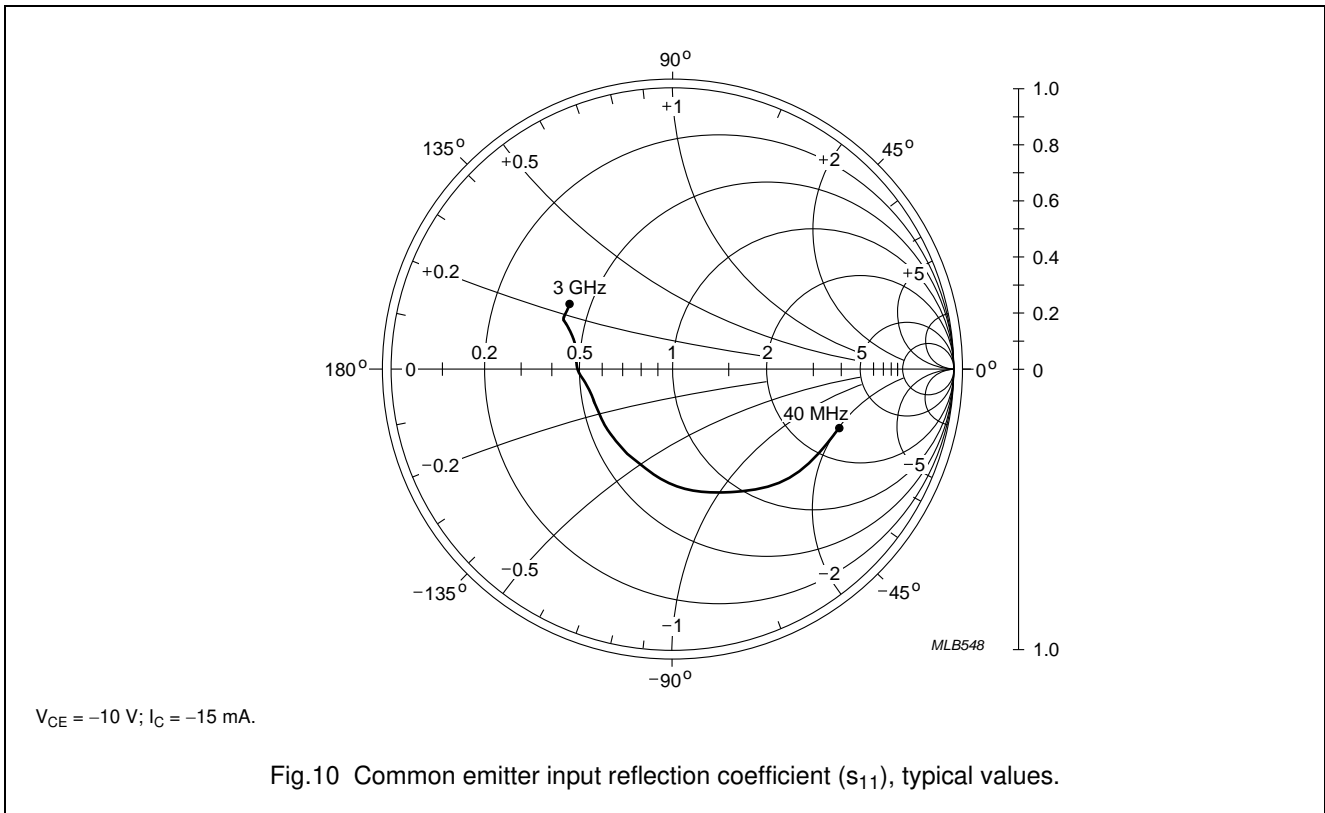
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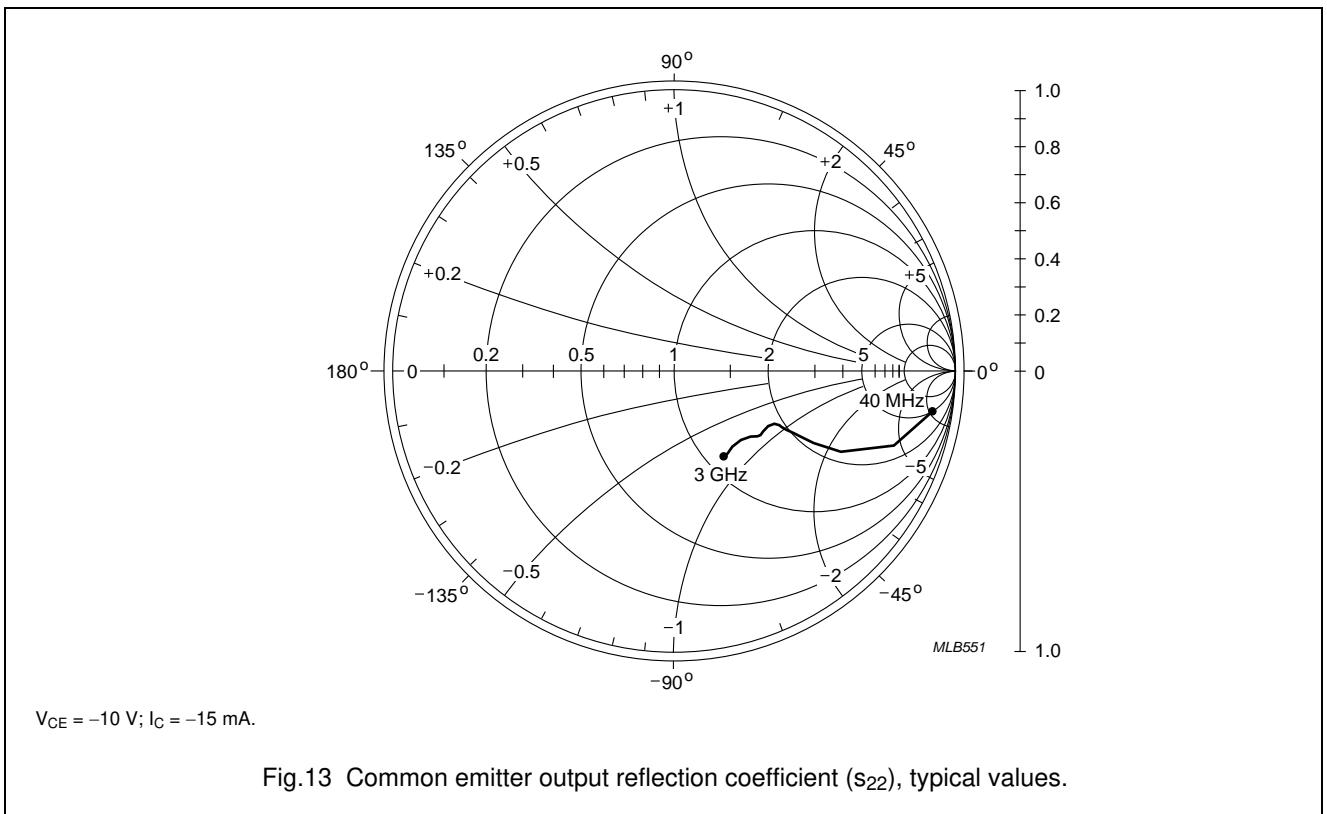
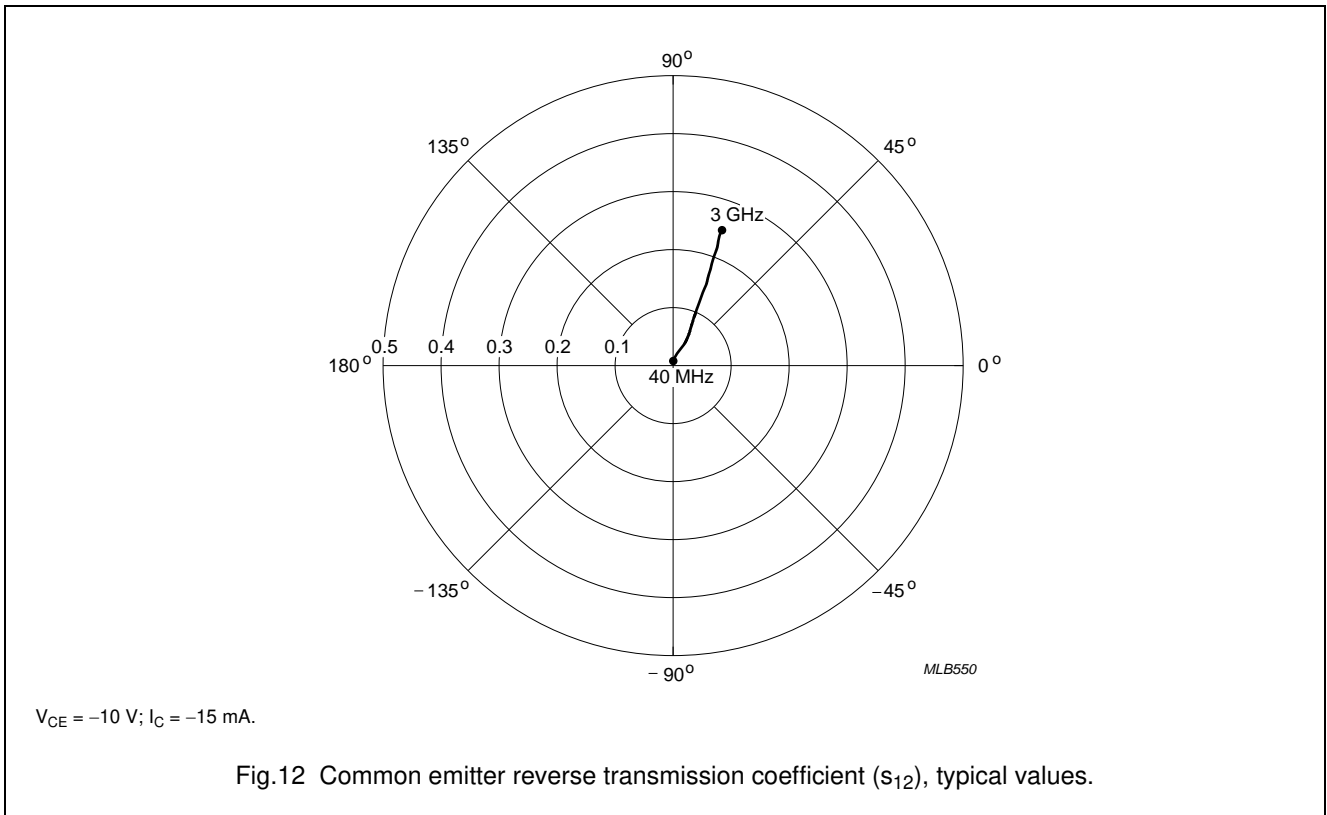
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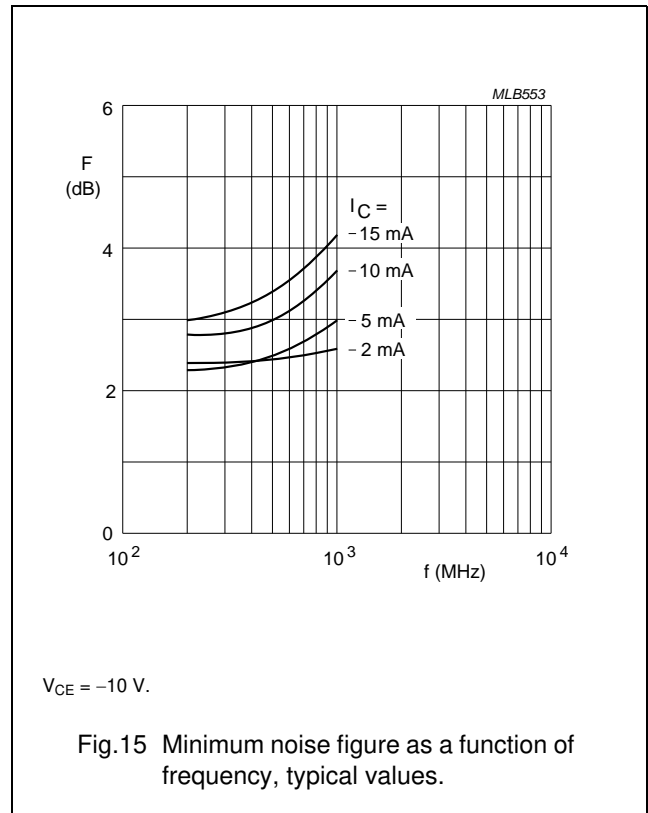
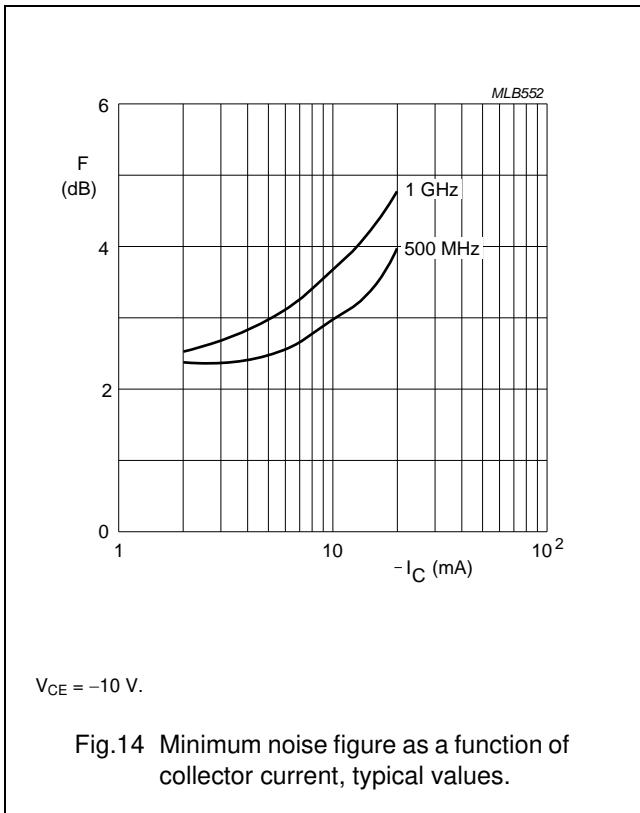
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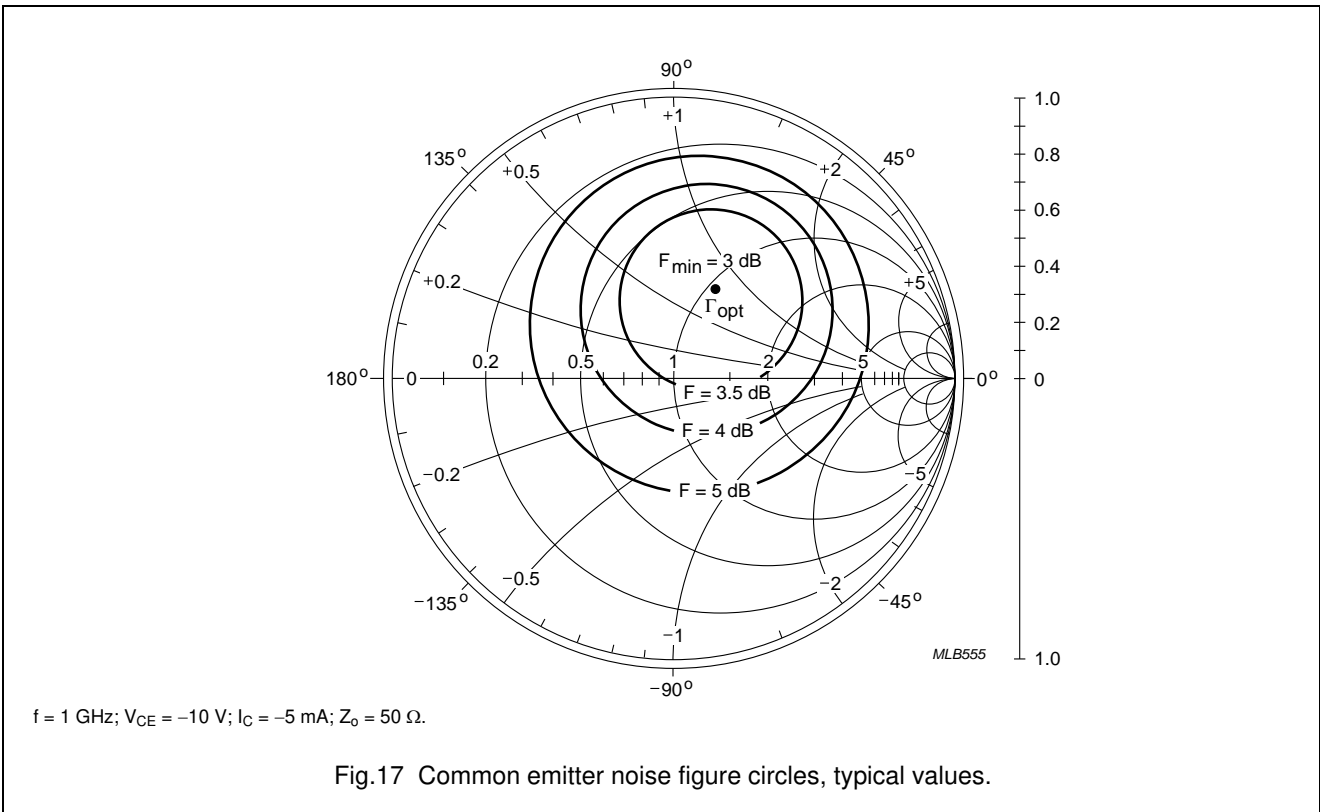
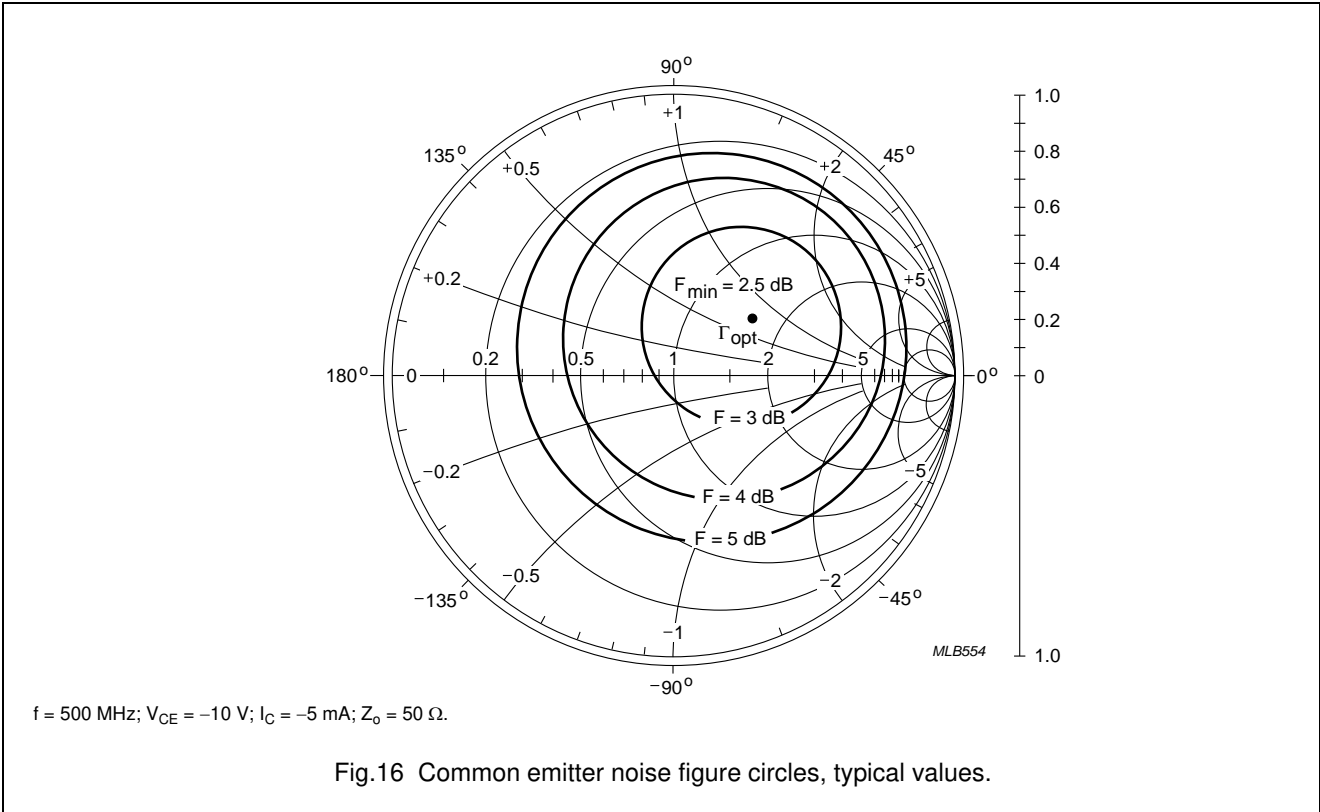
PNP 4 GHz wideband transistor

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BFT92W

SPICE parameters for the BFT92W crystal

SEQUENCE No.	PARAMETER	VALUE	UNIT
1	IS	437.5	aA
2	BF	33.58	–
3	NF	1.009	–
4	VAF	23.39	V
5	IKF	99.53	mA
6	ISE	87.05	fA
7	NE	1.943	–
8	BR	4.947	–
9	NR	1.002	–
10	VAR	3.903	V
11	IKR	5.281	mA
12	ISC	35.88	fA
13	NC	1.393	–
14	RB	5.000	Ω
15	IRB	1.000	μA
16	RBM	5.000	Ω
17	RE	1.000	Ω
18	RC	10.00	Ω
19 ⁽¹⁾	XTB	0.000	–
20 ⁽¹⁾	EG	1.110	eV
21 ⁽¹⁾	XTI	3.000	–
22	CJE	746.6	fF
23	VJE	600.0	mV
24	MJE	0.357	–
25	TF	17.49	ps
26	XTF	1.354	–
27	VTF	155.6	mV
28	ITF	1.000	mA
29	PTF	45.00	deg
30	CJC	937.1	fF
31	VJC	396.4	mV
32	MJC	0.200	–
33	XCJC	0.106	–
34	TR	8.422	ns
35 ⁽¹⁾	CJS	0.000	F

SEQUENCE No.	PARAMETER	VALUE	UNIT
36 ⁽¹⁾	VJS	750.0	mV
37 ⁽¹⁾	MJS	0.000	–
38	FC	0.768	–

Note

1. These parameters have not been extracted, the default values are shown.

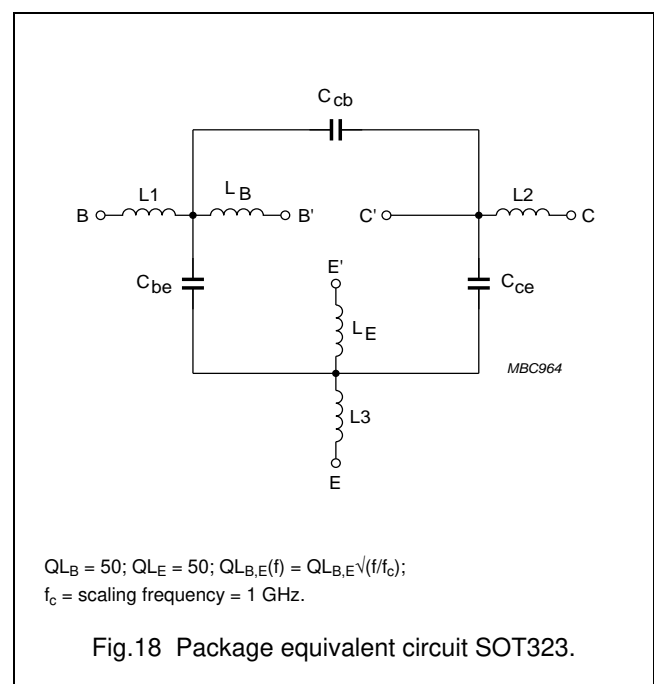


Fig.18 Package equivalent circuit SOT323.

List of components (see Fig.18)

DESIGNATION	VALUE	UNIT
C _{be}	2	fF
C _{cb}	100	fF
C _{ce}	100	fF
L1	0.34	nH
L2	0.10	nH
L3	0.34	nH
L _B	0.60	nH
L _E	0.60	nH

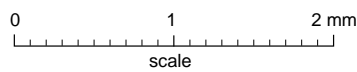
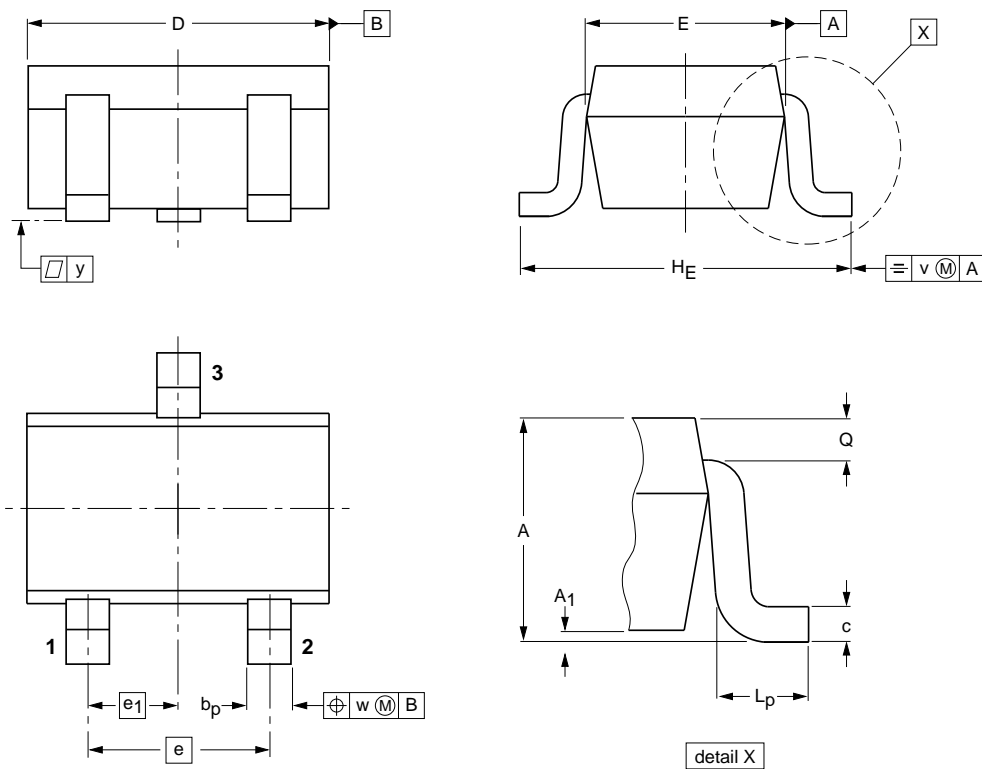
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BFT92W

PACKAGE OUTLINE

Plastic surface-mounted package; 3 leads

SOT323



DIMENSIONS (mm are the original dimensions)

UNIT	A	A ₁ max	b _p	c	D	E	e	e ₁	H _E	L _p	Q	v	w
mm	1.1 0.8	0.1	0.4 0.3	0.25 0.10	2.2 1.8	1.35 1.15	1.3	0.65	2.2 2.0	0.45 0.15	0.23 0.13	0.2	0.2

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT323			SC-70			04-11-04 06-03-16

PNP 4 GHz wideband transistor

BFT92W

DATA SHEET STATUS

DOCUMENT STATUS ⁽¹⁾	PRODUCT STATUS ⁽²⁾	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

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PNP 4 GHz wideband transistor

BFT92W

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This data sheet was changed to reflect the new company name NXP Semiconductors, including new legal definitions and disclaimers. No changes were made to the technical content, except for package outline drawings which were updated to the latest version.

Contact information

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Printed in The Netherlands

R77/01/pp14

Date of release: May 1994